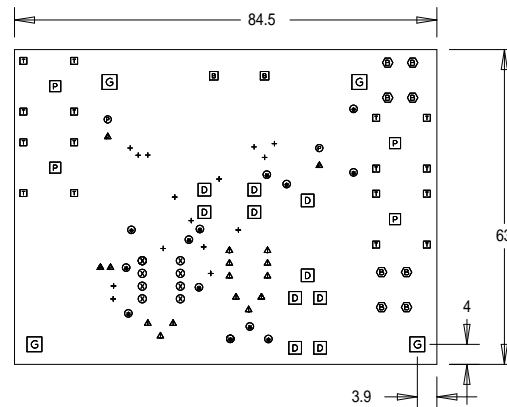



SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE

MATERIAL	FR4 IMPROVED (low CTE)
BOARD THICKNESS	1.6mm /63mils
STACKUP	DF /2LAYERS
MINIMAL GAP	210um /8.0mils
MINIMAL SLIVER	210um /8.0mils
COPPER THICKNESS	35um(1oz)at START
FINISH THICKNESS	CHEMICAL NiAu
SOLDER MASK	GREEN TOP & BOT
SILKSCREEN	WHITE TOP
ALL BOARD ELECTRICALLY TESTED	
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK	



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILLIMETERS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
+	0.5	+0.0/-0.0	PLATED	15
⊙	0.8	+0.0/-0.0	PLATED	2
▲	0.8	+0.0/-0.0	PLATED	6
▲	0.8	+0.0/-0.0	PLATED	4
▲	0.9	+0.0/-0.0	PLATED	6
⊙	1.0	+0.0/-0.0	PLATED	13
⊞	1.1	+0.0/-0.0	PLATED	2
⊙	1.4	+0.0/-0.0	PLATED	8
⊞	1.4	+0.0/-0.0	PLATED	16
⊙	2.0	+0.0/-0.0	PLATED	8
⊞	2.2	+0.0/-0.0	PLATED	4
⊞	2.25	+0.05/-0.05	PLATED	10
⊞	3.0	+0.0/-0.0	NON-PLATED	4

1.0		44/2017
indice	Description	Date
Controle par :	Autorise par:	
 ON semiconductor		Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE
Subc. DYPE TECH		Dessine: e B
Board: VM UC384x EVB-A-TLS		Echelle: 1/1
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